

| PREPEARED BY | APPROVED BY |
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DOC.NO.: ISS:F12F0.25

HALOGEN

Changed Contents



Description

F12F Series are the fuses set the industry standard for performance, reliability and quality. The solder-free design provides excellent on-off and temperature cycling characteristics during use and also makes our SMD fuses more heat and shock tolerant than typical subminiature fuses.

| Electrical Characteristics | | | | | |
|----------------------------|-------------|------------|-------|--|--|
| Rated Current | 1.0In | 2.5In | 3.5In | | |
| 250mA | 4 hour min. | 5 sec max. | - | | |

Features

- > AEC-Q200 Automotive Grade Certified
- Rapid interruption of excessive current
- Compatible with reflow and wave solder
- Ceramic and glass construction
- One time positive disconnect
- Lead Free and Halogen free material

Specifications

| Specification | | | | | | | |
|---------------|------------------------|--------------------------|--------------------------------------|---|---------------------------------|--|------------------|
| Part No. | Rated Voltage DC | Rated Curren t (A) | Breaking Capacity(A) ¹ | Typical Cold. Resistance (mOhms) ² | Typical Voltage Drop (mV) | Typical Pre- Arcing I ² t (A ² Sec) ³ | Alpha Marking |
| F12F0.25 | 72V | 250mA | 50A@72Vdc | 3608 | 1407 | 0.0004 | .25 |

1. DC Interrupting Rating (Measured at rated voltage, time constant of less than 50 microseconds, battery source)

2. DC Cold Resistance are measured at <10% of rated current in ambient temperature of 25° C

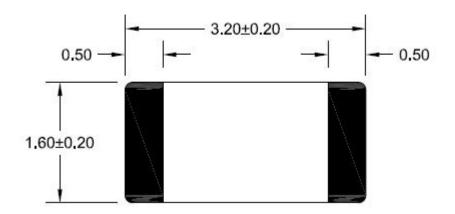
3. Typical Pre-arcing I²t are measured at 10In Current

Specifications are subject to change without notice. Application testing is strongly recommended.

Dimension

Drawing not to scale (Unit: mm) Top

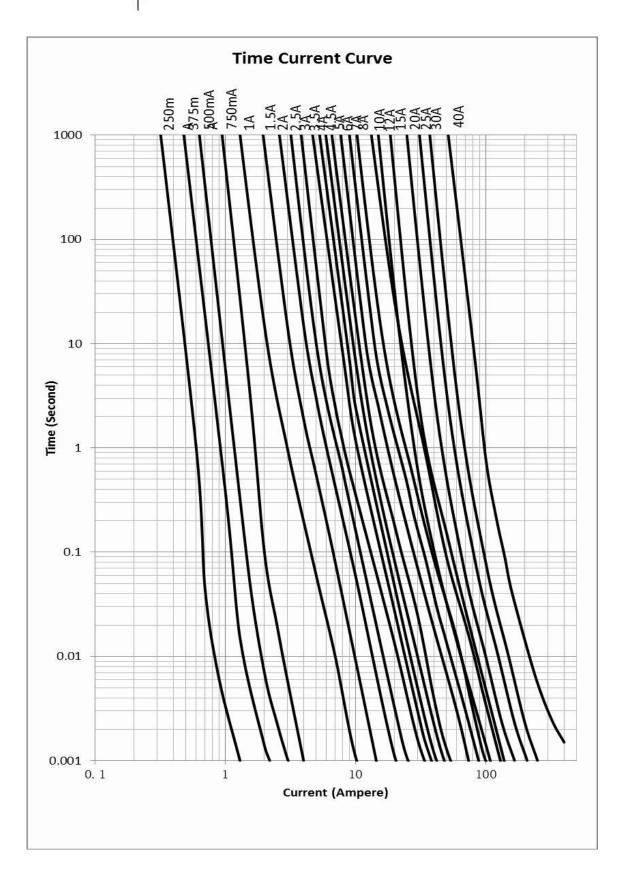
view



Side view: 250mA~750mA/20A~40A

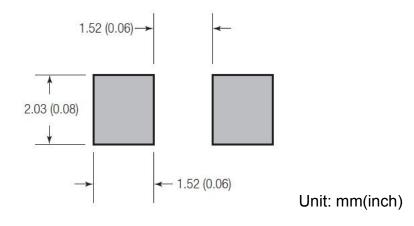








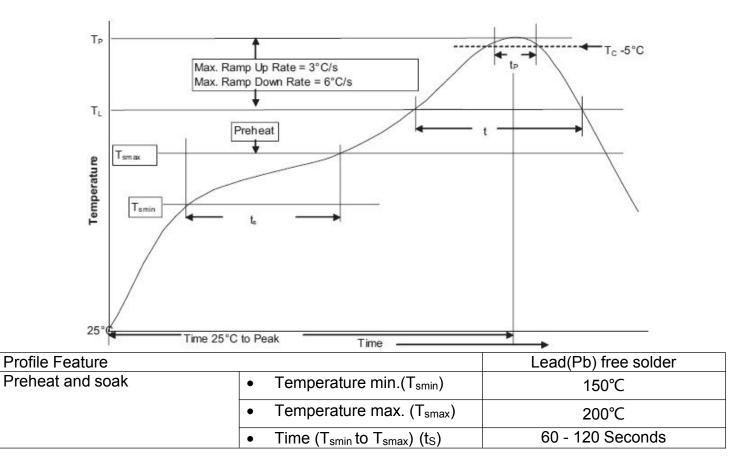
Recommended land pattern



Soldering method

- Wave solder
 - Reservoir temperature: 260°C
 - Time in reservoir: 10 seconds maximum
- Infrared reflow
 - Temperature: 260°C
 - Time: 30 seconds maximum

Solder reflow profile



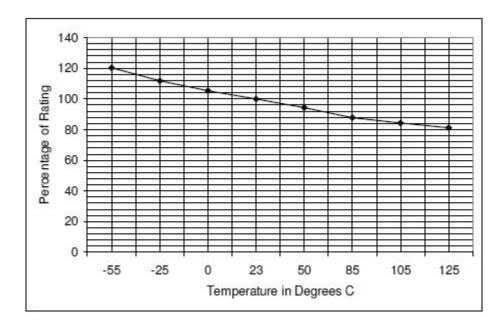


| Average ramp up rate T _{smax} to T _p | 3°C / Second Max. | |
|---|-------------------|--|
| Liquidous temperature (T _L) | 217℃ | |
| Time at liquidous (t _L) | 60 - 150 Seconds | |
| Peak package body temperature (T _P) | 260°C | |
| Time (t _P) within 5°C of the specified classification temperature (T _C) | 30 Seconds | |
| Average ramp-down rate (T _P to T _{smax}) | 6°C / Second Max. | |
| Time (25°C to Peak Temperature) | 8 Minutes Max. | |

Temperature Derating Curve

Normal ambient temperature: 23+/-3°C

Operating temperature: -55 ~ 125°C, with proper correction factor applied



Package

3000 fuses on 8mm tape-and-reel on a 7 inch (178mm) reel per EIA Standard 481.

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